### SN74LVC139A-Q1 DUAL 2-LINE TO 4-LINE DECODER/DEMULTIPLEXER

SCAS782B - SEPTEMBER 2004 - REVISED JANUARY 2008

- Qualified for Automotive Applications
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 6.2 ns
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Level Per AEC-Q100 Classification
  - 2000-V (H2) Human-Body Model
  - 200-V (M3) Machine Model
  - 1000-V (C5) Charged-Device Model

#### D OR PW PACKAGE (TOP VIEW) 16 🛮 V<sub>CC</sub> 1G 15 2<del>G</del> 1A 🛮 2 1B 14 🛮 2A **3** 13 **∏** 2B 1Y0 12 ] 2Y0 1Y1 11 2Y1 1Y2 10 2Y2 1Y3 9 1 2Y3 GND ∏8

#### description/ordering information

This dual 2-line to 4-line decoder/demultiplexer is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The device comprises two individual 2-line to 4-line decoders in a single package. The active-low enable  $(\overline{G})$  input can be used as a data line in demultiplexing applications. This decoder/demultiplexer features fully buffered inputs, each of which represents only one normalized load to its driving circuit.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

#### **ORDERING INFORMATION**†

T <sub>A</sub>	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Reel of 2500	SN74LVC139AQDRQ1	LVC139AQ
-40°C to 125°C	TSSOP – PW	Reel of 2000	SN74LVC139AQPWRQ1	LC139AQ

<sup>&</sup>lt;sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

## FUNCTION TABLE (each decoder/demultiplexer)

	INPUTS	i		OUTPUTS						
G	SEL	ECT		0011015						
G	ВА		Y3	Y2	Y1	Y0				
L	L	L	Н	Н	Н	L				
L	L	Н	Н	Н	L	Н				
L	Н	L	Н	L	Н	Н				
L	Н	Н	L	Н	Н	Н				
Н	Х	Χ	Н	Н	Н	Н				

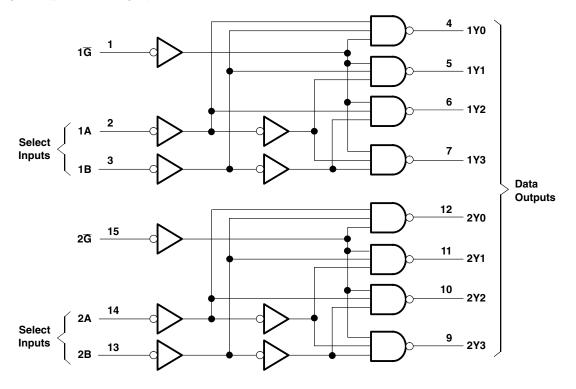


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6.5 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 6.5 V
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, I <sub>O</sub>	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): D package	73°C/W
(see Note 3): PW package	108°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V	Complement	Operating	1.65	3.6	V	
$V_{CC}$	Supply voltage  High-level input voltage  Low-level input voltage  Input voltage  Output voltage  High-level output current  Low-level output current  Input transition rise or fall rate  Operating free-air temperature	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
	digh-level input voltage  Low-level input voltage  Input voltage  Dutput voltage  High-level output current  Low-level output current	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	$V_{CC}$	V	
		V <sub>CC</sub> = 1.65 V		-4		
	High lavel autout august	$V_{CC} = 2.3 \text{ V}$		-8	A	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12	mA	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 1.65 V		4		
	Lave lavel autout auroat	V <sub>CC</sub> = 2.3 V		8	A	
l <sub>OL</sub>	Low-level output current	$V_{CC} = 2.7 \text{ V}$		12	mA	
		V <sub>CC</sub> = 3 V				
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	125	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEGT COMPLETIONS		$T_A = -40^\circ$	°C TO 12	5°C	$T_A = -40$	°C TO 8	5°C	
PARA	AMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
		$I_{OH} = -100  \mu A$	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V <sub>CC</sub> - 0.2			
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			1.2			
.,		$I_{OH} = -8 \text{ mA}$	2.3 V	1.7			1.7			V
$V_{OH}$		10 4	2.7 V	2.1			2.2			V
		$I_{OH} = -12 \text{ mA}$	3 V	2.3			2.4			
		I <sub>OH</sub> = -24 mA	3 V	2.1			2.2			
		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2			0.2	
		I <sub>OL</sub> = 4 mA	1.65 V			0.45			0.45	
$V_{OL}$		I <sub>OL</sub> = 8 mA	2.3 V			0.7			0.7	V
		I <sub>OL</sub> = 12 mA	2.7 V			0.4			0.4	
		I <sub>OL</sub> = 24 mA	3 V			0.55			0.55	
lı	All inputs	V <sub>I</sub> = 5.5 V or GND	3.6 V			±5			±5	μΑ
I <sub>CC</sub>		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			10			10	μΑ
$\Delta I_{CC}$		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500			500	μΑ
Ci		V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		5			5		pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



## SN74LVC139A-Q1 DUAL 2-LINE TO 4-LINE DECODER/DEMULTIPLEXER

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# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

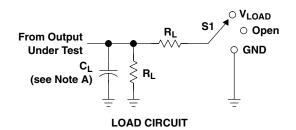
PARAMETER	FROM	TO	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
$t_{pd}$ A or B $Y$ $1$ 1	A or B	V	1	8.8	1	7.7	
	6.7	1	6.2	ns			
t <sub>sk(o)</sub>						1	ns

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	$V_{CC} = 3.3 \text{ V}$	LINUT
	FARAIVIETER	CONDITIONS	TYP	V <sub>CC</sub> = 2.5 V         V <sub>CC</sub> = 3.3 V           TYP         TYP           29.5         30.5         pF	UNIT	
C <sub>pd</sub>	Power dissipation capacitance	f = 10 MHz	28.5	29.5	30.5	pF

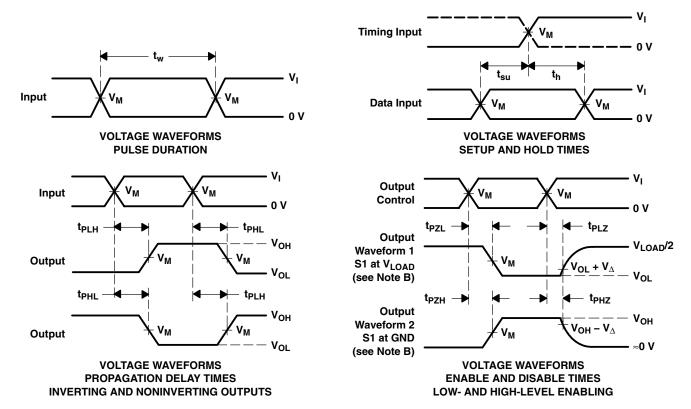


#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

V	INPUTS		.,	v	•		.,	
	V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	$V_{LOAD}$	CL	$R_L$	$V_\Delta$
	2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
	3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ MSL rating/		Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
CLVC139AQPWRG4Q1	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC139AQ
CLVC139AQPWRG4Q1.B	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC139AQ
SN74LVC139AQPWRQ1	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC139AQ
SN74LVC139AQPWRQ1.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC139AQ
SN74LVC139AQPWRQ1.B	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC139AQ

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN74LVC139A-Q1:

◆ Catalog : SN74LVC139A

NOTE: Qualified Version Definitions:

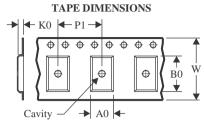
• Catalog - TI's standard catalog product

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVC139AQPWRG4Q1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC139AQPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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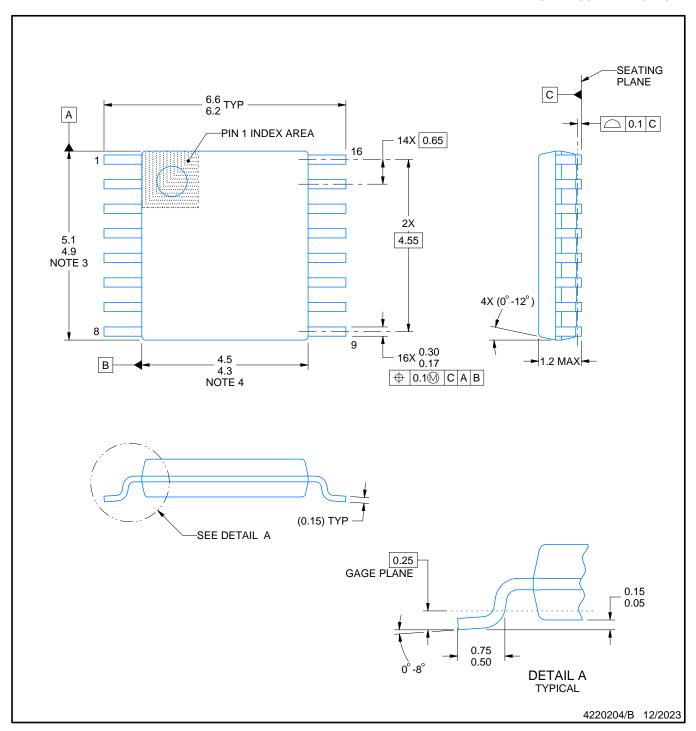


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CLVC139AQPWRG4Q1	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LVC139AQPWRQ1	TSSOP	PW	16	2000	353.0	353.0	32.0



SMALL OUTLINE PACKAGE



#### NOTES:

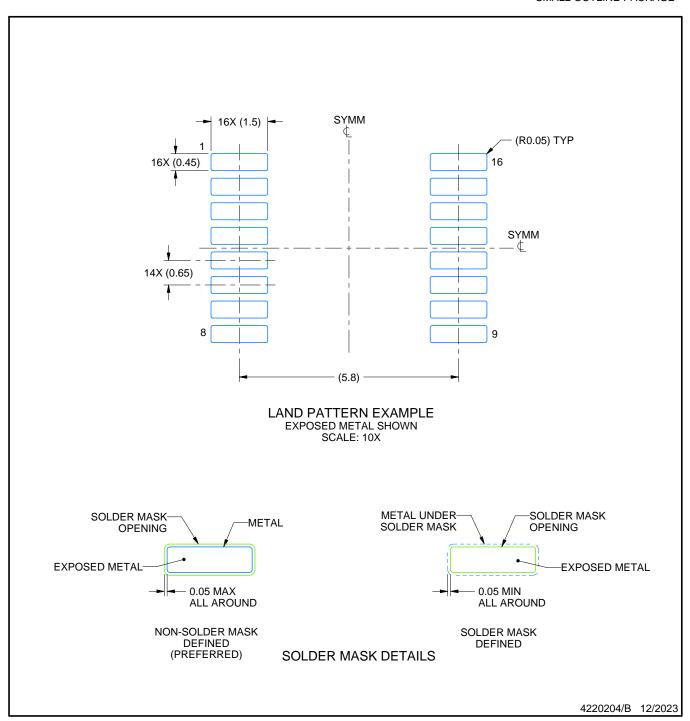
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

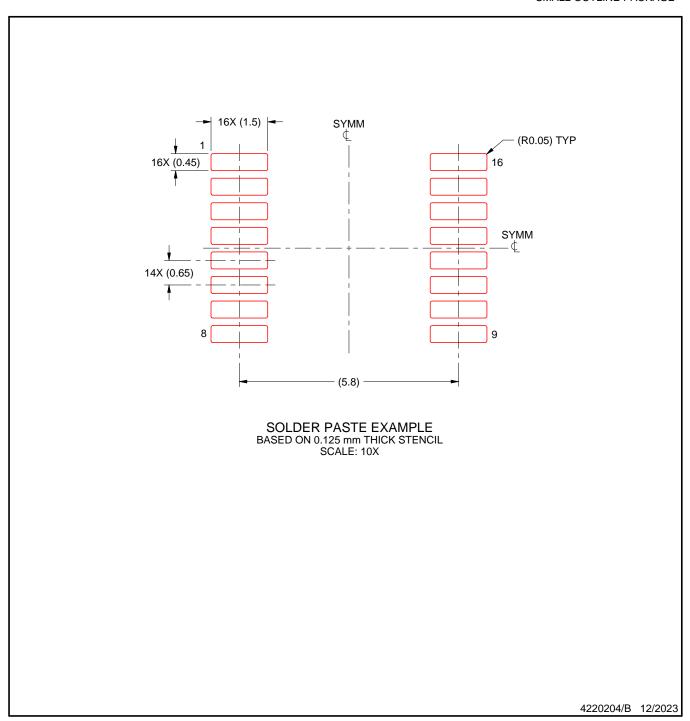


NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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